



## Material Content Data Sheet



<b>Sales Product Name</b>				BSZ086P03NS3 G		<b>Issued</b>		27. September 2017	
<b>MA#</b>				MA001321070					
<b>Package</b>				PG-TSDSON-8-2		<b>Weight*</b>		38.76 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.835	4.73	4.73	47344	47344	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		54		
	non noble metal	zinc	7440-66-6	0.008	0.02		216		
	non noble metal	iron	7439-89-6	0.168	0.43		4326		
wire	non noble metal	copper	7440-50-8	6.808	17.57	18.03	175653	180249	
	non noble metal	copper	7440-50-8	0.036	0.09	0.09	918	918	
	encapsulation	organic material	carbon black	1333-86-4	0.034	0.09		868	
	plastics	epoxy resin	-	1.733	4.47		44727		
	inorganic material	silicondioxide	60676-86-0	15.062	38.87	43.43	388646	434241	
leadfinish	non noble metal	tin	7440-31-5	0.387	1.00	1.00	9989	9989	
plating	noble metal	silver	7440-22-4	0.963	2.48	2.48	24837	24837	
solder	non noble metal	tin	7440-31-5	0.037	0.10		950		
	noble metal	silver	7440-22-4	0.046	0.12		1187		
	non noble metal	lead	7439-92-1	1.758	4.54	4.76	45350	47487	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28		
	non noble metal	zinc	7440-66-6	0.004	0.01		111		
	non noble metal	iron	7439-89-6	0.086	0.22		2225		
	non noble metal	copper	7440-50-8	3.501	9.03	9.26	90338	92702	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		49		
	non noble metal	zinc	7440-66-6	0.008	0.02		195		
	non noble metal	iron	7439-89-6	0.151	0.39		3894		
	non noble metal	copper	7440-50-8	6.127	15.81	16.22	158095	162233	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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